

APD3224MBC BLUE

Features

- 3.2x2.4mm SMT LED, 2.4mm THICKNESS.
- LOW POWER CONSUMPTION.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 1500PCS / REEL.

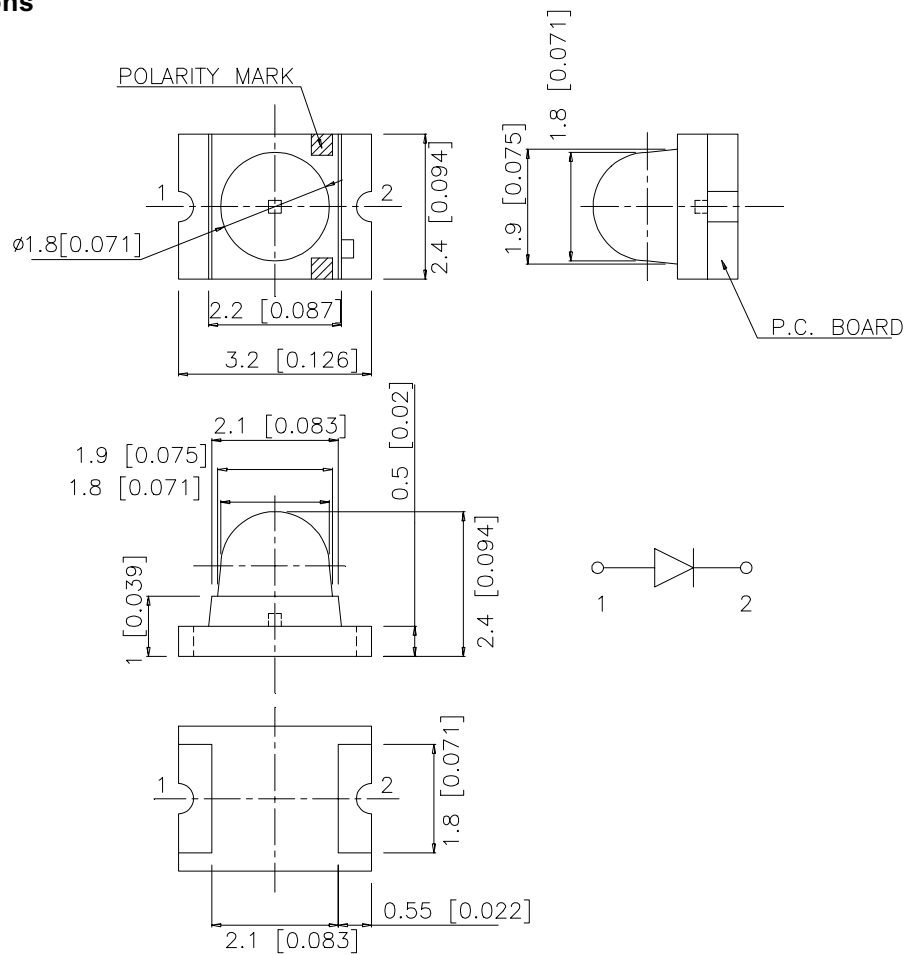
Description

The Blue source color devices are made with GaN on SiC Light Emitting Diode.

Static electricity and surge damage the LEDs. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.1 (0.004") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
APD3224MBC	BLUE (GaN)	WATER CLEAR	36	80	20°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Absolute Maximum Ratings at T_A=25°C

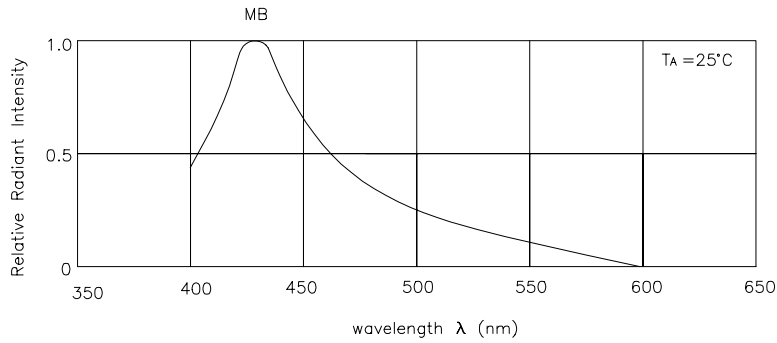
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Blue	430		nm	I _F =20mA
λ _D	Dominant Wavelength	Blue	466		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Blue	60		nm	I _F =20mA
C	Capacitance	Blue	100		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	Blue	3.8	4.5	V	I _F =20mA
I _R	Reverse Current	Blue		10	μA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Blue	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

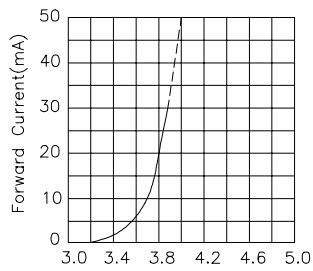
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

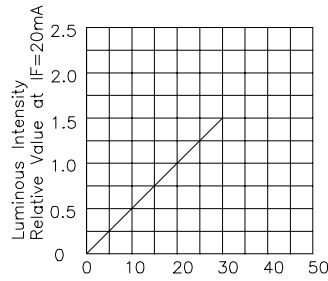


RELATIVE INTENSITY Vs. WAVELENGTH

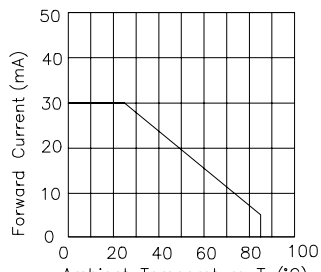
Blue APD3224MBC



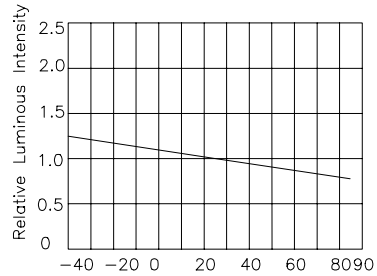
FORWARD CURRENT Vs. FORWARD VOLTAGE



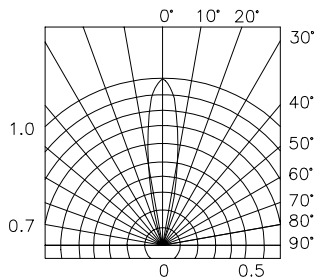
LUMINOUS INTENSITY Vs. FORWARD CURRENT



FORWARD CURRENT DERATING CURVE



LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE

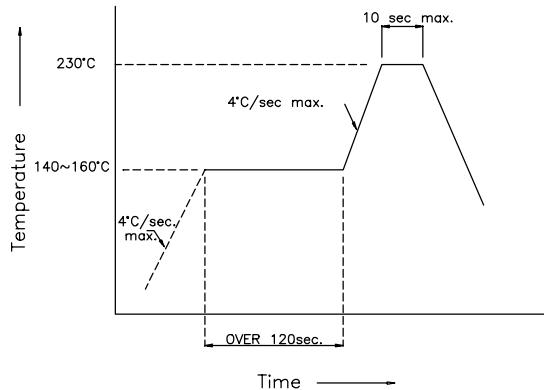


SPATIAL DISTRIBUTION

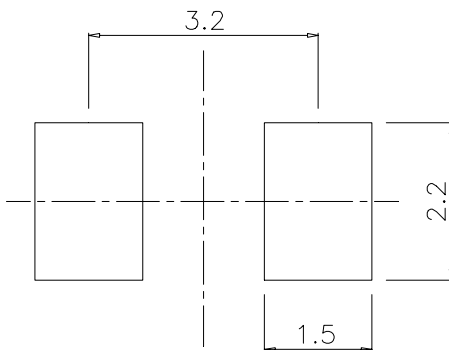
APD3224MBC

SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

